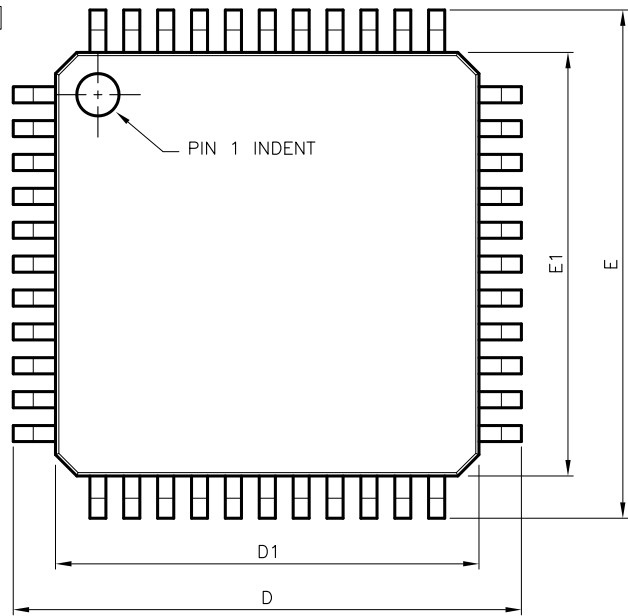
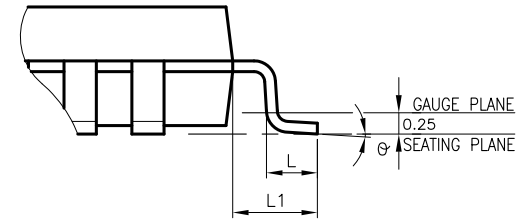
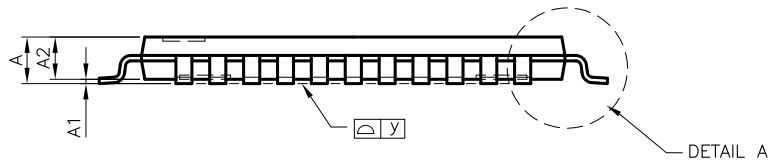
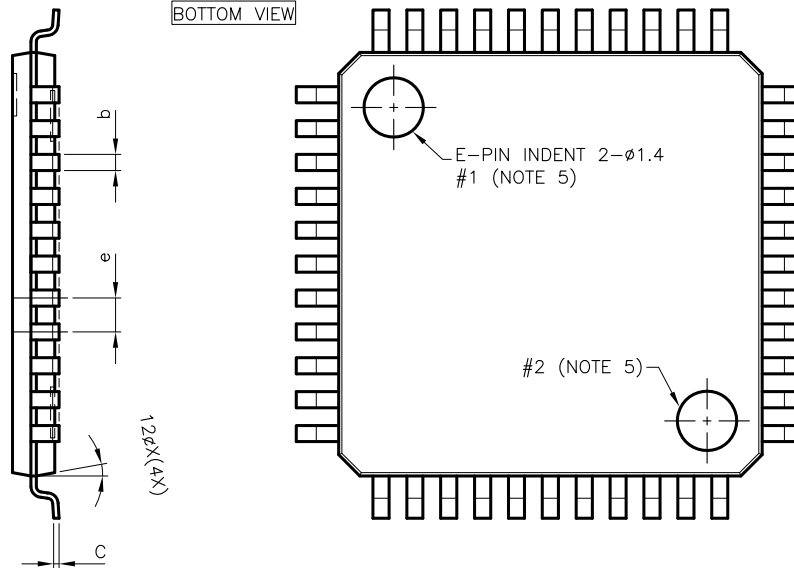


TOP VIEW



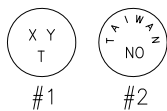
BOTTOM VIEW



DETAIL A

NOTE :

1. CONTROLLING DIMENSION : mm
2. LEAD FRAME MATERIAL : COPPER C7025
3. PACKAGE DIMENSION EXCLUSIVE MOLDING FLASH ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE
4. RESIN PROTRUSION BETWEEN LEAD TO LEAD TO BE 0.08 mm MAX
5. BOTTOM E-PIN INDENT ARE MARKED AS BELOW :



X : A, B, C, ...
Y : 1 ~ 10
NO : DENOTE MOLD SET NUMBER

6. ALL EDGE CORNER TO BE R 0.20 MAX.
7. JEDEC NUMBER : MS-026

SYMBOL	DIMENSIONS IN MILLIMETERS		
	MIN.	NOM.	MAX.
A	—	—	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b	0.30	0.37	0.45
C	0.09	—	0.20
E	—	12.00	—
E1	—	10.00	—
D	—	12.00	—
D1	—	10.00	—
e	—	0.80	—
L	0.45	0.60	0.75
L1	—	1.00	—
∅	0°	3.5°	7°
y	0.0	—	0.10

CUSTOMER :

LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z.
PRECISION IND., LTD. TAICHUNG, TAIWAN, R. O. C.

APPROVED BY

DATE

TITLE:
44L TQFP PACKAGE OUTLINE
DRAWING(10x10x1.0 mm)
(2.0 mm FOOTPRINT)

DRAW BY:
Vicky Chen 7/21/98

CHECK BY:
Thomas Kao 7/24/98

APPROVAL:
Paul Liu 7/30/98

APPROVAL:
Barry Chen 7/31/98

DWG. NO. PO-TQFP-004

REV. 0

UNIT : mm

SCALE : 8/1

SHEET 1 OF 1